AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A flat transponder having an electronic circuit which is arranged in one of a layer ~~or in~~ and a layer composite and which contains at least one chip and conductor tracks or conductor wires, characterized in that the circuit is arranged in or on a circuit carrier [[(7)]] made of plastic, on whose two larger opposite outer surfaces a paper layer [[(6)]] is applied by lamination ~~is in each case applied~~.

2. (Currently Amended) The transponder as claimed in claim 1, ~~characterized in that~~ wherein the paper layer ~~(6) consists of~~ comprises coated paper.

3. (Currently Amended) The transponder as claimed in claim 1 [[or 2]], ~~characterized in that~~ wherein the circuit carrier ~~(7) consists of~~ comprises a layer in which an antenna [[(2)]] and a module [[(3)]] having module connections [[(4)]] are embedded.

4. (Currently Amended) The transponder as claimed in claim 1 [[or 2]], ~~characterized in that~~ wherein the circuit carrier [[(7)]] comprises at least two plastic films [[(7.1, 7.2)]], between which there are arranged an antenna [[(2)]] and a module [[(3)]] having module connections [[(4)]].

5. (Currently Amended) The transponder as claimed in ~~one of the preceding claims~~claim 1, ~~characterized in that~~ wherein the circuit carrier ~~(7) consists of~~ comprises polyethylene.

6. (Currently Amended) The transponder as claimed in ~~one of the preceding claims~~claim 1, ~~characterized in that~~ wherein notches [[(11)]] are introduced into at least one paper layer [[(6)]].

7. (Currently Amended) The transponder as claimed in claim 6, ~~characterized in that~~ wherein the notches [[(11)]] are made in the form of trenches having one of parallel [[or]] and V-shaped limits.

8. (Currently Amended) The transponder as claimed in claim 6 [[or 7]], ~~characterized in that~~ wherein the depth of the notches [[(11)]] is less than the thickness of the paper layer [[(6)]].

9. (Currently Amended) The transponder as claimed in claim 6 [[or 7]], ~~characterized in that~~ wherein the notches [[(11)]] penetrate through the paper layer [[(6)]] and penetrate into the adjacent layer of the circuit carrier [[(7)]].

10. (Currently Amended) The transponder as claimed in ~~one of claims 6 to 9~~claim 6, ~~characterized in that~~ wherein the notches [[(11)]] are applied at least one of at different intervals ~~and/or~~and with a different depth on the various sections of the paper layer [[(6)]] in order to create surface regions [[of]] having at least one of different flexibility ~~and/or~~and different flexibility directions.

11. (Currently Amended) The transponder as claimed in ~~one of the preceding claims~~claim 6, ~~characterized in that~~ wherein the notches [[(11)]] are arranged in the form of visible cut patterns ~~or symbols~~.

12. (Currently Amended) The transponder as claimed in ~~one of claims 1 to 11~~claim 1, ~~characterized in that~~ wherein the circuit is enclosed completely by the material of the circuit carrier [[(7)]].

13. (Currently Amended) The transponder as claimed in ~~one of claims 1 to 11~~claim 1, ~~characterized in that~~ wherein the module ~~(3) consists of~~ comprises a rigid body which is arranged

in an aperture which is located in the circuit carrier [[(7)]] and the paper layer [[(6)]] located above the ~~latter~~paper layer.

14. (Currently Amended) A method for the production of a transponder ~~as claimed in one of claims 1 to 13~~having an electronic circuit which is arranged in one of a layer and a layer composite and which contains at least one chip and conductor tracks or conductor wires, the method comprising:

~~characterized in that the~~ fitting the circuit ~~is fitted~~ in or on a circuit carrier [[(7)]] made of plastic; and

~~in each case~~ applying a paper layer ~~(6) is applied~~ to both sides of the circuit carrier [[(7)]] by lamination.

15. (Currently Amended) The method as claimed in claim 14, ~~characterized in that~~ wherein the lamination ~~is carried out by means of~~ comprises:

hot pressing [[of]] the circuit carrier [[(7)]] and paper layers [[(6)]] together between one of laminating plates [[or]] and laminating rolls.

16. (Currently Amended) The method as claimed in claim 14, ~~characterized in that~~ wherein notches [[(11)]] are introduced on at least one surface side of the laminate [[(1)]].

17. (Currently Amended) The method as claimed in claim 16, ~~characterized in that~~ wherein the notches [[(11)]] are produced during the lamination by ~~means of~~ notching webs fitted in an elevated manner to one of [[the]] laminating plates [[or]] and laminating rolls, the form of said notching webs corresponds to the form of the notches [[(11)]] to be produced.

18. (Currently Amended) The method as claimed in claim 16, ~~characterized in that~~ wherein the notches [[(11)]] are introduced by ~~means of~~ at least one of knife [[or]] and saw cuts after the lamination.

19. (Currently Amended) The method as claimed in claim 16, ~~characterized in that~~ wherein the notches [[(11)]] are introduced by ~~means of~~ laser cuts after the lamination.

20. (Currently Amended) The method as claimed in claim 16, ~~characterized in that~~ wherein the notches[[(11)]] are produced by ~~combined introduction by means of~~ at least one of a knife, saw, and laser introduced by laminating plates during the lamination ~~and by knife, saw or laser cuts after the lamination~~.